2021 MEDIA KIT

A 3D Community
Introduction
Content
Contributing Editors
Award Program
Readership

Demographics
Community Platform
Editorial Content

Yearbook
Advertising
Marketing Opportunities

Contact Françoise von Trapp
3dincites.com
978.340.0773
francoise@3dincites.com
BE PART OF THE 3D COMMUNITY

3D InCites is Your Go-to Resource for Everything 3D:

- An online community platform for the discussion of heterogeneous integration and related semiconductor manufacturing technologies.
- Supported by an advisory board of heterogeneous integration experts from R&D, manufacturing, market research, design, and test.

Come home to 3D InCites and find:
- Recommended reads
- Featured podcasts and videos
- Member spotlights
- Original content on trending topics
- Contests
- Career opportunities
- SemiSisters
- …and More

“3D INCITES BRINGS TO LIFE THE PEOPLE, THE PERSONALITIES, THE IDEAS, AND THE MINDS BEHIND OUR INDUSTRY IN A UNIQUELY PERSONAL WAY.”

RAJIV ROY
WHY 3D INCITES?

The semiconductor industry is going vertical, and 3D InCites is your connection!

3D InCites is THE HUB for 3D and Heterogeneous Integration activities.

3D InCites has served the advanced packaging and 3D integration community for over 10 years and is a leading resource read by CEOs, executives, technical experts, trade association members and more — all of whom are interested in your company, organization or service to help them in driving the future of semiconductor packaging technology.

WE TAKE YOU WHERE THE ACTION IS

All the critical CONVERSATIONS happen here
SHARE, ENGAGE AND COLLABORATE with your customers
LEARN from the EXPERTS
As a brand, 3D InCites is recognized throughout the semiconductor industry for its active representation at heterogeneous integration and related technology events and trade shows around the globe including:

- International Wafer Level Packaging Conference
- MEMS and Sensors Executive Congress
- SEMICON Europa
- IEDM
- ISS
- IMAPS Device Packaging Conference
- IEEE Electronic Components Technology Conference
- SEMICON West
- MEPTEC Events
- International Semiconductor Executive Summit
- And more

What we cover...
- Market intelligence
- Application drivers
- Technology trends
- Emerging processes
- Design challenges and solutions
- Advances in metrology, inspection, and test

“3D INCITES DOES AN AMAZING JOB COVERING ADVANCED PACKAGING, HETEROGENEOUS INTEGRATION, SMART MANUFACTURING AND MORE FROM A DIFFERENT PERSPECTIVE THAN THE TRADE PUBLICATIONS. THEIR ENGAGING ARTICLES PROVIDE INSIGHT AND ANALYSIS ON SEMICONDUCTOR INDUSTRY TOPICS IMPORTANT TO THOSE INVESTING IN R&D, DESIGN AND MANUFACTURING. IN THIS ERA OF RADICAL CHANGE IN THE HOW AND WHEN INFORMATION GETS TO US, 3D INCITES IS A KEY PLACE TO VISIT WHEN ANALYZING TRENDS AND STAYING UP ON THE NEWS.”

HEIDI HOFFMAN, SEMI

Endorsed by:

ECTC

International Microelectronics Assembly and Packaging Society

Bringing together the entire microelectronics supply chain™

semi

IWLPC

International Wafer-Level Packaging Conference
Blogs that inform, innovate and inspire

3D InCites is host to monthly blogs tackling the most timely and critical conversations. Our in-house contributors have years of experience and thoughtful insight, which is viewed monthly by our readers worldwide. You too can contribute as a guest blogger and showcase your products and services to our community.

Françoise von Trapp: Francoise in 3D
Queen of 3D, Françoise von Trapp, focuses on the trends driving the adoption of heterogeneous integration and 3D integration.

Herb Reiter: 3D In Context
A long-time evangelist of 3D integration technologies, Herb Reiter provides a holistic perspective and insight on how to bring 3D integration to the masses.

Phil Garrou: Packaging InCites from the Leading Edge
Count on Phil’s thrice-monthly blog to bring you technical expertise on leading-edge IC packaging and the changes occurring in the IC world that underpin it.

Guests: From Different Dimensions
Guest blogger, Dean Freeman, and others, offer insights into the semi market, its technology drivers and the implications on 3D and heterogeneous integration technologies.

“FOR OVER 10 YEARS, WE’VE COUNTED ON 3D INCITES’ BLOGGERS TO PROMOTE AND PARTICIPATE IN OUR FLAGSHIP EVENTS. WE APPRECIATE THEIR UNIQUE PERSPECTIVE THAT FOCUSES ON THE PEOPLE WHO MAKE OUR INDUSTRY THRIVE.”

MICHAEL O’DONOGHUE, EXECUTIVE DIRECTOR, IMAPS
INDUSTRY ACHIEVEMENT RECOGNITION

The 3D InCites Awards

Each year, we celebrate your efforts in innovation by hosting the 3D InCites Awards, which recognize excellence in heterogeneous integration technologies. A portion of the proceeds benefit a STEM program.

Nominated by your peers, and voted on by a panel of experts, awards are presented in the following categories:

- Device of the Year
- Process of the Year
- Device Manufacturer of the Year
- Startup of the Year
- Equipment Supplier of the Year
- Materials Supplier of the Year
- EDA Provider of the Year
- Research Institute of the Year
- Engineer of the Year
3D InCites is the authority for heterogenous integration and 3D technology.

Our Community is broad and varied.

Visitors count on 3D InCites to help them make informed decisions for their companies.

Our top followers include:
- Avid Investors
- Business professionals
- Technophiles
- Avid news readers
- Auto enthusiasts

The primary interests of those followers include:
- Computers, electronics/electronic components, chips & processors
- Investment services
- Computer accessories and components
- Consumer electronics/Mobile phones
- Internet and telecom
- Software
WE ATTRACT A GLOBAL AUDIENCE

You’ll Benefit from World Wide Exposure

In a 12 month period:
More than **140,000** users from all over the world* visit 3D InCites nearly **200,000** times and view more than **270,000** pages

We reach the regions that matter most to the semiconductor industry

- **60%** United States
- **26%** Asia
- **11%** Europe
- **3%** ROW

Shouldn’t YOUR COMPANY have a presence?

Contact Françoise von Trapp

3dincites.com  978.340.0773  francoise@3dincites.com
JOIN OUR COMMUNITY

We are committed to the semiconductor industry and always seek out ways to be a better partner in the community!

Now offering a community platform full of benefits:

COMMUNITY MEMBERSHIP
$1,000/year

- Company profile page on website
- Logo on home page
- Participate in weekly member spotlight
- Your events promoted on our calendar
- Recruitment portal (Job posting/Search)
- 10% discount advertising/sponsorships (awards program excluded)
- One complimentary Video of the Week
- Your logo in annual print edition community ad
- Social media mentions throughout the year
- *Membership fee waived for advertisers who spend $6000 or more

* before discounts

“Being a member of the 3D inCites community gives us opportunities to share and be featured in exciting content that reaches a global audience of semiconductor professionals. As our business in the heterogeneous integration space grows, it is great to have a platform like 3D inCites, where we can engage with our industry peers.”

LAURENT GIAI-MINIET, CEO
ERS electronic GmbH
3D InCites accepts contributions for guest blogs, executive viewpoints, and technology features.

All relevant ideas will be considered for publication. Submit all abstracts to the Editor.

**Blog Frequency**

<table>
<thead>
<tr>
<th>Name</th>
<th>Frequency</th>
</tr>
</thead>
<tbody>
<tr>
<td>Francoise in 3D</td>
<td>Varies</td>
</tr>
<tr>
<td>IFTLE</td>
<td>3x month</td>
</tr>
<tr>
<td>Herb Reiter</td>
<td>3x month</td>
</tr>
<tr>
<td>Dean Freeman</td>
<td>1x month</td>
</tr>
</tbody>
</table>

**Accepting Technical Contributions on the following topics for publication throughout 2021:**

**Focus on Chiplet Architectures**
- Design challenges and solutions
- Processes and technologies
- Test challenges and solutions
- Emerging trends and target applications
- Market drivers
- Executive viewpoint

**3D Integration Updates**
- Thin-wafer handling solutions
- Hybrid bonding
- Advances in through silicon via technologies
- Inspecting 3D architectures
- Materials innovation
- 3D integration and quantum computing
- Market drivers
- Executive viewpoint

**Heterogeneous Integration**
- HI roadmap update
- Process improvements for fan-out wafer level/panel level
- Advances in process control
- Materials innovation
- Glass as a substrate solution
- New approaches for system-in-package
- Market drivers
- Executive viewpoint

**MEMS and Sensors**
- Process improvements
- Integration trends
- MEMS and 3D systems
- Automotive MEMS packaging
- Market drivers
- Executive viewpoint

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Accepting Technical Contributions on the following topics for publication throughout 2021:

Megatrend Thought Leadership Topics
- Impact of the coronavirus on the semiconductor industry
- Automotive market trends
- Smart mobility
- Artificial intelligence
- Machine learning
- Telemedicine
- Smart manufacturing
- Standards
- Doing business in China
- Sustainability

SemiSisters
- Building an inclusive workplace
- Recruitment tips for hiring and retaining women
- Building your network
- D&I update: how are we doing as an industry?
- Employee empowerment
- Navigating your career
- D&I event promotion
- Personal experiences of underrepresented minorities
- SemiSister of the Year Award
- Executive viewpoint

Editorial Guidelines

Don’t see a topic that fits your technology or expertise? Pitch us your idea: Send a 300-word abstract of your contributed piece to francoise@3DInCites.com. Contributions should include:

- Posts: 500-1500 words, with up to five figures provided in .jpg or .png format, and under 2MB file size.
- White papers can be any length but should be submitted as a downloadable .pdf file. Include a 500-word executive summary.
- Please provide a 1200 X 700 conceptual image or “beauty shot” (1200 x 700 pixels wide).
- Videos: up to minutes in length. MP4 file up to 50MB or a YouTube link.
- Author headshot, title, email and brief bio to create a profile. This is your byline and all posts by you will be linked to it.

Contributors retain their own copyright however we do prefer that feature contributions be original for 3D InCites. Subsequent publication in other media sources should include the statement that this article “appeared first on 3D InCites” with a link to the post.
A lot can happen in a year. And 2020 is certainly no exception. COVID-19 had an enormous impact on our ability to distribute print issues of the Yearbook at industry events. However, we are excited to report that we will move forward with a digital-only version of the 2021 Yearbook, set for publication by the end of January.

Join us as we take a look back at 2020, and a look forward to what 2021 will bring.

**Cover Feature: A Visit to a Community Leader**

Each year, we select one of our 3D InCites community leaders to learn more about them: how the company started, what inspires its leaders and what is driving them forward to the next great thing.

Executive viewpoints on this year’s hot topics may include:
- How We Navigated COVID-19 and What 2021 Will Bring
- What’s Next for 3D ICs?
- What’s Different about Chiplet Design and Integration?
- Why your OSAT Needs to Be Smarter

Technology Features
- Reliability Testing: More Important than Ever
- An Update on Fan-Out Technology
- Novel Approaches to Wafer Handling

SemiSister Spotlight
- The SemiSisters of 2020
- How to Hire and Retain an Inclusive Workforce
- Networking Your Way to Success

**The Year in Photos**

And as all but IMAPS DPC went virtual, capturing our usual collection of photos to remember the year is going to be a challenge. We invite all our community members to contribute photos for consideration from 2020.

**Contributed Technology Features (pitch us your idea – select from topics above)**

Best of 3D InCites 2020 Blog Posts … and more!

Advertisers may submit editorial content for consideration based on the above topics. Articles will also be published throughout 2021 on 3D InCites.
Limited quantity show distribution (if possible) at IMAPS DPC, ECTC 2020, and IMAPS SiP, SEMICON West, IMAPS Symposium, IWLPC, and more ...

Ad rates reflect at least a 20% discount over the 2020 print issue. Additionally, digital ads will link directly to your dedicated URL.

**Yearbook Ad Rates**

<table>
<thead>
<tr>
<th>SIZE/LOCATION</th>
<th>RATE</th>
</tr>
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<tbody>
<tr>
<td>Back Cover</td>
<td>$4,000</td>
</tr>
<tr>
<td>Inside Front Cover</td>
<td>$3,200</td>
</tr>
<tr>
<td>Inside Back Cover</td>
<td>$3,600</td>
</tr>
<tr>
<td>Two-page spread</td>
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<tr>
<td>Full Page</td>
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<tr>
<td>Half-Page Vertical</td>
<td>$1,450</td>
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<tr>
<td>Half-Page Horizontal</td>
<td>$1,450</td>
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<tr>
<td>Quarter Page</td>
<td>$800</td>
</tr>
</tbody>
</table>

**Ad specs:**
- JPG file type
- RGB color, no bleed or trim (although it is helpful to leave .25 to .5 inch margins on all sides)
- 144 dpi minimum

**Editorial contributions due:**
Nov. 30, 2020

**Ad space close:**
Dec. 15, 2020

**Camera-ready materials due:**
Jan. 11, 2021
New website design and layout with targeted advertising opportunities.
Position your company alongside thought leaders in heterogeneous integration and 3D technology.
Ensure your company message reaches key decision makers.
Align your company brand with the credible and esteemed content of 3D InCites.

**RUN OF SITE**
(Limited to three advertisers per position)

**LEADERBOARD BANNER**
(Six month minimum)
- $1300/month
- (970x90)

**BOX BANNER**
- $1000/month
- (300x250)

**TAGS - $500/MONTH PER TAG**
Create a targeted campaign. Your ad will appear in the body of the post based on the tag. Ad size: 970 x 90. Choose from:
- Advanced Packaging
- Heterogeneous integration
- Semiconductor
- Chiplets
- 3D
- Fan-out wafer level packaging
- MEMS and Sensors
- EDA
- Process Control
- Inspection
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CATEGORIES - $1000/MONTH PER CATEGORY

Side bar ad across category (300x250).
Main body ad on top-level category page (970x90). Choose from:
- Design
- Devices
- Manufacturing
- Materials
- Processes and Technology
- Test and Inspection
- News
- Event Coverage
SPONSORED CONTENT RATES

Gain exposure through our well-read content

SPONSOR YOUR FAVORITE BLOGGER
$1000/month
Make your company the exclusive name sponsor of your favorite blogger or bring your own! Six month minimum commitment.

CUSTOM WHITE PAPER PROGRAM
starting at $3000/
6 month minimum
Branded White Paper featured on the home page. Includes:
- Landing page with registration
- Lead capture/reporting
- Each paper featured in one eNL Blast
- Promoted on LinkedIn, and Twitter

SPONSORED VIDEO/PODCAST
$1000/video or episode
Promotion of your company’s video or podcast on our home page. Featured for one week, Title link for 30 days. Includes promotion on LinkedIn and Twitter.

EBLAST OF YOUR CONTENT
$1000/blast
You provide the content and we will do the rest. Includes formatting.

SPONSORED BLOG POSTS
$500/issue
Your company blog post will be featured in 3D InCites In Review. Feature image, and headline links to the full post on your company blog.

3D INCITES IN REVIEW - WEEKLY ENL
$500/issue, 8-week minimum
With a 35% open rate, you can be sure that by advertising in our weekly eNL, you’re putting your brand in front of the most engaged members of the semiconductor industry every week.